



# 100% Material Declaration Data Sheet CSG280

PK204 (v1.0) October 5, 2006

Material Declaration Data Sheet

**Average Weight: 0.6180 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.0253</b>	<b>4.10%</b>
	Silicon	7440-21-3	100.00		0.0253	
<b>Die Attach Material</b>					<b>0.0033</b>	<b>0.53%</b>
	Resin	Trade Secret	22.00		0.0007	
	Silver	7440-22-4	78.00		0.0025	
<b>Mold Compound</b>					<b>0.2890</b>	<b>46.76%</b>
	Resin	Trade Secret	12.00		0.0347	
	Silica	60676-86-0	88.00		0.2543	
<b>Laminate</b>					<b>0.1770</b>	<b>28.65%</b>
	Copper	7440-50-8	16.72	Metal Layer	0.0296	
	Nickel	7440-02-0	4.41	Metal Layer	0.0078	
	Gold	7440-57-5	0.79	Metal Layer	0.0014	
	Board	Trade Secret	63.62		0.1126	
	Solder Mask (EP)	Trade Secret	14.46		0.0256	
<b>Gold Wire</b>					<b>0.0108</b>	<b>1.74%</b>
	Gold	7440-57-5	100.00		0.0108	
<b>Solder Balls</b>					<b>0.1126</b>	<b>18.22%</b>
	Tin	7440-31-5	95.50		0.1076	
	Silver	7440-22-4	4.00		0.0045	
	Copper	7440-50-8	0.50		0.0006	

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1

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
10/5/06	1.0	Initial release.